

Atty. Docket No. CPAC 1017-3
Appl. No. 10/632,568

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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SEP 11 2006

Applicant: Marcos Karnozos)

) Examiner: Douglas M. Menz

Application No.: 10/632,568)

) Group Art Unit: 2824

Filed: August 2, 2003)

) Date: September 11, 2006.

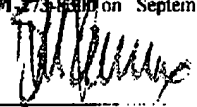
Title: **Semiconductor multi-package module
having package stacked over ball grid array
package and having wire bond interconnect
between stacked packages**)

) **CONFIRMATION NO. 2603**

) CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this correspondence is being facsimile transmitted to
Examiner Menz in the United States Patent and Trademark Office, at the Central
Fax no. 571-273-8300 on September 11, 2006.

Signed


Bill Kennedy

COMMISSIONER FOR PATENTS
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AMENDMENT

Dear Sir:

In response to the Office action mailed March 10, 2006, kindly amend the application as follows.

Amendments to the claims are reflected in the **Listing of Claims**, which begins on page 2 of this paper.

Remarks begin on page 6 of this paper.